

ABSTRACT

To prevent, in a multilayer wiring board to which a semiconductor chip is flip-chip bonded, occurrence of cracks in the board at portions adjacent to electrode pads due to a difference in thermal expansion coefficient between the semiconductor chip and the board. A multilayer wiring board (20) of the present invention has features that electrode pads (22) corresponding to electrodes of a semiconductor chip (25) located near an outer periphery (29) of the semiconductor chip each have an oblong shape, openings (35) of a solder resist (23) are each smaller than the oblong shape, and the center (B) of the opening is located to be offset from the center (A) of the oblong shape by a distance (L4) in a direction (30) toward the center of the semiconductor chip. Therefore, in the multilayer wiring board of the present invention, thermal stresses applied to portions (L3) of the electrode pads (22) on the board near the outer periphery of the semiconductor chip are relaxed. Consequently, the multilayer wiring board of the present invention can prevent occurrence of cracks in the board at portions adjacent to the electrode pads near the outer periphery of the semiconductor chip due to a difference in thermal expansion coefficient between the semiconductor chip and the board.